



Product Change Notification: BLAS-16DMDR130

Date:

19-Mar-2025

Product Category:

Power Discrete Components

Notification Subject:

CCB 7483 Final Notice: Implement packing material changes for selected PSDS and SIC products available in SOT-227, TO-220, TO-247, TO-263 and TO-268 packages at FSTS and TEAM final test sites.

Affected CPNs:

[BLAS-16DMDR130_Affected_CPN_03192025.pdf](#)

[BLAS-16DMDR130_Affected_CPN_03192025.csv](#)

Notification Text:**PCN Status:**

Final Notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Implement packing material changes for selected PSDS and SIC products available in SOT-227, TO-220, TO-247, TO-263 and TO-268 packages at FSTS and TEAM final test sites.

Pre and Post Summary Changes:

	Pre Change	Post Change
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Inner Box	Microsemi branded label	Microchip branded label
Inner Box Label	Microsemi standard label	Microchip standard label
	With dimensional changes for SOT-227 package for TEAM final test site. See Pre and Post Change for Comparison.	
ESD Label	Microsemi standard label	New inner box with ESD symbol
Tube	Microsemi branded label	Microchip branded label
Desiccant	Silica	Clay
Packing Method	See Pre and Post Change Summary for Comparison.	

Impacts to Datasheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by implementing packing material changes for selected PSDS and SIC products.

Change Implementation Status:

In Progress

Estimated First Ship Date:

24 April 2025 (date code: 2517)

Note: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2024					April 2024				
Work Week	09	10	11	12	13	14	15	16	17	18
Final PCN Issue Date				x						
Estimated Implementation Date									x	

Method to Identify Change:

Traceability code and packing material

Qualification Report:

Not Applicable

Revision History:

March 19, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-16DMDR130 Pre and Post Change_Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MSC040SMA120J

MSC2X100SDA070J

MSC2X100SDA120J

MSC2X101SDA070J

MSC2X101SDA120J

MSC2X61DC120J

MSC2X30SDA070J

MSC2X30SDA120J

MSC2X30SDA170J

MSC2X31SDA070J

MSC2X31SDA120J

MSC2X31SDA170J

MSC2X50SDA070J

MSC2X50SDA120J

MSC2X50SDA170J

MSC2X51SDA070J

MSC2X51SDA120J

MSC2X51SDA170J

MSC017SMA120J

MSC025SMA120J

MSC080SMA120J

MSC080SMA120JS15

MSC2X21DC120J

MSC015SMA070J

MSC035SMA170J

MSC2X51SDA070J-C25

MSC2X101SDA070J-C25

MSC2X51SDA120J-C25

MSC080SMA120JS15-C25

MSC010SDA070K

MSC010SDA120K

MSC015SDA120K

MSC020SDA120K

MSC030SDA070K

MSC030SDA120K

MSC010SDA070KVAO

MSC020SDA120KVAO

MSC010SDA120KVAO

MSC030SDA120KVAO

MSC015SDA120KVAO

MSC030SDA070KVAO

MSC010SDA120B

MSC010SDA170B

MSC015SDA120B

MSC050SDA070B

MSC050SDA120B

MSC050SDA170B

MSC020SDA120B

MSC030SDA120B

MSC030SDA170B

MSC010SDA070B

MSC030SDA070B

MSC010SDA070BVAO

MSC020SDA120BVAO

MSC030SDA120BVAO

MSC050SDA120BVAO

MSC010SDA120BVAO

MSC015SDA120BVAO

MSC030SDA070BVAO

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MSC050SDA070BVAO

MSC035SMA170B

MSC090SMA070B

MSC040SMA120B

MSC180SMA120B

MSC015SMA070B

MSC050SDA070BCT

MSC017SMA120B

MSC050SDA120BCT

MSC360SMA120B

MSC060SMA070B

MSC030SDA120BCT

MSC750SMA170B

MSC025SMA120B

MSC080SMA120B

MSC010SDA070BCT

MSC030SDA070BCT

MSC035SMA070B

MSC015SMA070BVAO

MSC035SMA070BV01

MSC035SMA070B4

MSC035SMA170B4

MSC040SMA120B4

MSC015SMA070B4

MSC017SMA120B4

MSC060SMA070B4

MSC750SMA170B4

MSC025SMA120B4

MSC080SMA120B4

MSC090SMA070SA

MSC180SMA120SA

Date: Tuesday, March 18, 2025

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MSC360SMA120SA

MSC750SMA170SA

MSC010SDA070S

MSC035SMA070S

MSC090SMA070S

MSC035SMA170S

MSC180SMA120S

MSC040SMA120S

MSC015SMA070S

MSC050SDA070S

MSC050SDA120S

MSC360SMA120S

MSC017SMA120S

MSC030SDA070S

MSC060SMA070S

MSC020SDA120S

MSC750SMA170S

MSC025SMA120S

MSC030SDA120S

MSC080SMA120S

MSC040SMA120S/TR

CCB 7483
Pre and Post Change Summary
PCN# BLAS-16DMDR130



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Inner Box

Pre Change

For FSTS & Team Pacific : The printing of inner box is Microsemi logo



Post Change

Change the printing of inner box to Microchip logo



Note: Not to scale


Inner Box Label – FSTS (IC)

Pre Change

For PSDS


LOT NO.:	C5281/C5202L96.1
W/O NO.	M00098358
SUBCON REFERENCE: T0247 3L	
DATE CODE : 1517	QA DATE: 4/28/2015
DIE VOLT : 3555-120/1613C-120	
QTY: 485	
APT25GR120BD15	
BOX NO. : 01 OF 01	
QA STAMP:	
CUSTOMER: MICROSEMI PHILIPPINES	

For SiC

(1P) CATALOG P/N: MSC040SMA120B4	
(1T) LOT NO.: 240900025000FSTS	(Pb) (e3) RoHS (50)
(P) CUST. P/N: -	(Q) QTY
MSL: -	960
PKG: T0247	
LEAD: 2	
SEAL DATE: 06/19/23	D/C QTY
WAFER QTY: -	2322 933
WAFER REV: -	2321 27
RECERT D/C: -	- -
WAFER LOT: -	- -
MPC: 1G0059T4CA00	
ID# : (001) TRACE CODE: 2322P17, 2321ABC	MADE IN PHILIPPINES

Post Change

For SiC : Remain the same (Already apply to Microchip)
For PSDS : Change to Microchip label

(1P) CATALOG P/N: MSC040SMA120B4	
(1T) LOT NO.: 240900025000FSTS	(Pb) (e3) RoHS (50)
(P) CUST. P/N: -	(Q) QTY
MSL: -	960
PKG: T0247	
LEAD: 2	
SEAL DATE: 06/19/23	D/C QTY
WAFER QTY: -	2322 933
WAFER REV: -	2321 27
RECERT D/C: -	- -
WAFER LOT: -	- -
MPC: 1G0059T4CA00	
ID# : (001) TRACE CODE: 2322P17, 2321ABC	MADE IN PHILIPPINES

Note: Not to scale

Inner Box Label – FSTS (Saw Die)

Pre Change

Chip Tray Label






Description:	<u>MICROCHIP</u>
M Lot:	<u>FSTS242300039.000</u>
Qty:	<u>175</u>
Foundry Lot:	<u>U4119</u>
P/N	<u>MSC035SMA170D/S</u>
Date:	<u>09/15/2023</u>
D/C:	<u>2336</u>

Inner box Label (SIC only)

(1P) CATALOG P/N: MSC025SMA120D/S	
(1T) LOT NO.: 242700017000FSTS	
(P) CUST. P/N: -	
MSL: - PKG: - LEAD: -	 RoHS  (Q) QTY 6383
SEAL DATE: 10/26/23 WAFER QTY: - WAFER REV: A RECERT D/C: - WAFER LOT: U43317	 D/C QTY 2340 6383
MPC: 1G013902XA00	
ID#: (001) TRACE CODE: 2340DM2	
	MADE IN PHILIPPINES

Post Change

For Inner box Label : Remain the same (Already apply to Microchip)
For Chip Tray Label : Change to Microchip label

(1P) CATALOG P/N: ABCDEFGHIJKL-BB-CC-DDDD-EEEE-FF		 D/C QTY 1407 250 1408 1000 1509 1250	
(1T) LOT NO.: 114601899000MTAI	 MSL: 3/260 C PKG: TFBGA LEAD: 48		(Q) QTY 2500
(P) CUST. P/N: ABCDEFGH IJKLMNOP QIRSTUV REV A			
MPC: ABCDEFGHJKLMNO	SEAL DATE: MM/DD/YY WAFER QTY: - WAFER REV: - RECERT D/C: - WAFER LOT: -		
ID#: (001) TRACE CODE: 1407B1R,1408B1Q,1509A3R	 B00234/T C09 B00234/T C09	MADE IN THAILAND	

100 mm.

60 mm.

Note: Not to scale

Inner Box Label – TEAM PACIFIC

Pre Change

For TO-268, TO-264, SOT-227, TO-247 (PSDS)

SHIPPING LABEL Batch: 1 / 1

Customer: MICROSEMI SEMICONDUCTORS MANILA, PHIL. INC.
MO No: MO866081/MO866082
RO/PO No: PDW080075715 / PQ104036429
Device No: Engineering MICROCHIP 450-4984 APT50GP60BG
Lot/Order No: J5885
Package Type: ENGG MICROCHIP TO247 3L 8W-10M AL 1D
Lot Qty: Box Qty: 387
Part #: N/A Date Code: 2438
Wafer Lot #: N/A

Ship To:
No. 6 Ring Road St., Light Industry and Science
Park II SEZ., Brgy Lamesa, Calamba City
Laguna 4027

QA Stamp

TSOP-2020-F2

For SOT-227, TO-268 (SIC)

(1P) CATALOG P/N: MSC017SMA120J
(1T) LOT NO.: TEAM243000006 000
(P) CUST. P/N: MSC017SMA120J
MPC: 1G0039TACA00
SEAL DATE: 10/27/23
WAVER QTY: 6
WAVER REV: A1
RECERT D/C: -
WAVER LOT: MCS0524048821.000
ID# (03.03.04.05.07.08) TRACE CODE: 2343M90
MADE IN PHILIPPINES

MSL: -
PKG SOT227
(Q) QTY
0

D/C QTY
2343 0

75 mm

100 mm

Post Change

All package

Change to Microchip label as below and For SOT-227, change the size to 100x60 to comply with microchip size

(1P) CATALOG P/N: ABCDEFGHIJKL-BB-CC-DDDD-EEEE-FF
(1T) LOT NO.: 114601899000MTAI
(P) CUST. P/N: ABCDEFGH IJKLMNO PQRSTUV REV A
MPC: ABCDEFGHJKLMNO
ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R

MSL: 3/260 C
PKG: TFBGA
LEAD: 48

SEAL DATE: MM/DD/YY
WAVER QTY: -
WAVER REV: -
RECERT D/C: -
WAVER LOT: -

RoHS E3

(Q) QTY
2500

D/C	QTY
1407	250
1408	1000
1509	1250

B00234/T C09
B00234/T C09



MADE IN THAILAND

100 mm.

60 mm.

Note: Not to scale

ESD Label

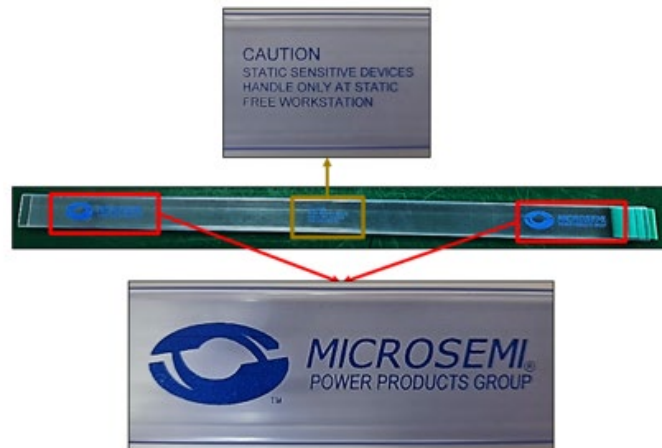
Pre Change	Post Change
<p>For FSTS and Team Pacific : Not comply at FSTS/Team Pacific</p> 	<p>To change the new inner box with ESD symbol</p> 

Note: Not to scale

Tube

Pre Change

For FSTS & Team Pacific : For SOT-227, the printing of tube is Microsemi logo





Post Change

Change the printing of tube to Microchip logo



Note: Not to scale

Desiccant

Pre Change	Post Change
<p>For FSTS: Already Clay For Team Pacific : The type of desiccant is “Silica”</p> 	<p>Change type of desiccant to “Clay”</p> 

Note: Not to scale